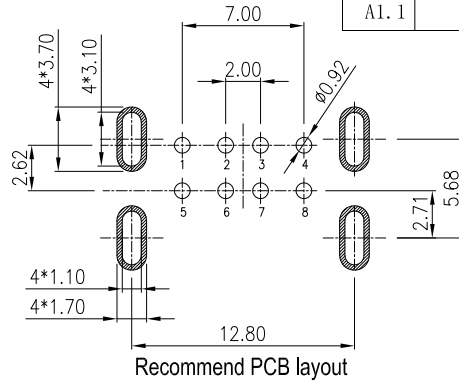
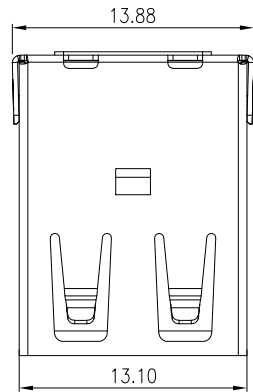


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2019/07/02	Phebe Su
A1			Change	2022/07/12	Ken Lin
A1.1			Add Dim.	2023/02/14	Ken Lin



NOTES:

1.MATERIAL SPECIFICATION:

1) INSULATION MATERIAL: THERMOPLASTIC UL94V-0. LCP BLACK

2) SHELL: SPCC,T:0.30mm
PLATING: NICKEL3) TERMINAL: COPPER ALLOY,T:0.25mm
PLATING: GOLD/TIN PLATED.

2.ELECTRICAL CHARACTERISTIC:

1)INSULATION RESISTANCE: 1000MΩ MIN.

2)CONTACT RESISTANCE: 30mΩ MAX.

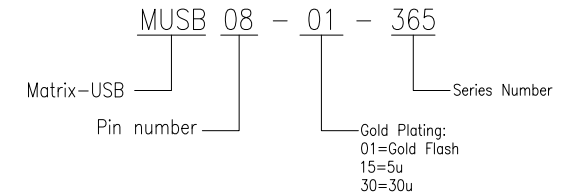
3)WITHSTANDING VOLTAGE: 500V AC.

3.MECHANICAL CHARACTERISTICS:

1)INSERTION FORCE: 3.57Kgf MAX.

2)EXTRACTION FORCE: 1.02Kgf MIN.

MATRIX PART NO:



USB 2.0 CONTACT PINS		
Pin NUMBER		SIGNAL NAME
1	5	VBUS
2	6	D-
3	7	D+
4	8	GND

HEAVEN INTERNATIONAL INC.

TOLERANCE: X.X ±0.20 X.XX ±0.15 X.XXX ±0.05 ANGLE: ±3°	DESIGN BY :	DATE :	PART NAME:	
	Ken Lin	2022/07/12	USB 2.0 双层90度DIP直脚無卷边	
UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY:	DATE :	PART NO.	MUSB08-01-365
	Vicky Hsieh	2022/07/12	MOLD NO.	NA
	APPROVED BY1:	DATE :	DRAW NO.	
	Richard Hsieh	2022/07/12	SHEET NO.	1 OF 1